

COPPER FOIL WITH EXTREMELY THIN ADHESIVE LAYER AND METHOD FOR PRODUCING THE COPPER FOIL WITH EXTREMELY THIN ADHESIVE LAYER

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A copper foil with an extremely thin adhesive layer (1) for use in a printed wiring board which has a copper foil (3) having not been subjected to a roughening treatment and, provided on one surface thereof an extremely thin primer resin layer for the purpose of securing good adhesion to a resin substrate, characterized in that it has a silane coupling agent layer (2) on the surface of the above copper foil having not been subjected to a roughening treatment having a surface roughness (Rz) of 2 μm or less and has on the silane coupling agent layer (2), an extremely thin primer resin layer (4) having a converted thickness of 1 to 5 μm ; and the like. The copper foil can be advantageously used as a copper foil which has not been subjected to a roughening treatment and has an extremely thin adhesive layer formed thereon.

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